

ABSTRACT

A general-purpose lead bending machine for electronic components that is capable of bending leads of various types of electronic components without a need of a great variety of benders. The machine includes a lead holding device for holding the distal end of a lead of an electronic component. A first driving mechanism causes the lead holding device to move along a first axis of travel. A second driving mechanism causes the lead holding device to move along a second axis of travel perpendicularly intersecting the first axis of travel. A control device controls the first driving mechanism and the second driving mechanism such that the lead holding device holding the lead of the electronic component moves along an approximately circular arc-shaped locus, thereby bending the lead of the electronic component.

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